

Workshop Reports

EMAP 2005

Mami Yamashita, Secretary

Dear Participants of EMAP 2005,

Thank you for joining the Conference once again. I have uploaded some of the pictures taken during the conference and the tour. Please take a look at the album and if you have any additions, please feel free to send me. I will be happy to work with them.

www.sms.titech.ac.jp/emap2005/album/album.html

The pictures of the general sessions are not in the order of the session program. I am sorry but I was just incapable of doing that! Please look for and find yourself.

Season's greetings and best wishes for a prosperous New Year!!

With best regards,

Mami Yamashita, Secretary
EMAP 2005 Secretariat

(See the Call for Papers for EMAP'06 in Hong Kong,
December 11-14, 2006, [later in this Newsletter](#))

Chapter News

Region 10 Chapter Activity Round-up

By Dr. P.B. Parikh, Region 10 News Coordinator

Singapore Chapter:

Dr. Wilson Tan, the newly elected chair of the chapter, has reported that the Singapore Chapter has successfully arranged four Technical talks as listed below during this quarter:

- (a) **Wire Bonding in Microelectronics with emphasis on Cu-Low K**
George G. Harman, Fellow IEEE, IMAPS, and NIST Fellow-Emeritus
- (b) **Lead-Free Solder Materials And Reliability Performance**
Dr John Pang, Nanyang Technological University, Singapore and Dr Rainer Dudek, IZM, Berlin, Germany
- (c) **Drop Impact Modeling and Testing for Handheld Electronic Products at Board and System Levels**
Dr. Tong Yan Tee, STMicroelectronics, Singapore, Dr. Chwee Teck Lim, National University of Singapore, and Dr. Jason Wu, Nokia, USA
- (d) **Wafer Level Packaging**
Dr. L. T. Nguyen, National Semiconductor Corp., and Dr. Kripesh Vaidyanathan, Institute of Microelectronics, Singapore

The chapter has also reported regarding the 3-day 7th Electronics Packaging Technology Conference (EPTC 2005) successfully organized on 7-9 December 2005 at the Grand Copthorne Waterfront, Singapore . The conference on 8th to 9th December was attended by a total of 265 delegates from 19 countries. In the keynote session, Dr Robert Darveaux from Amkor Technology discussed the "Current Trends and

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Critical Issues in Flip Chip Packaging" and Dr Chiang Shiuh-Kou from Prismark, gave an insight on "The Global Packaging Business and Technology". An invited talk on "CPMT and EPTC: A study in Symbiosis" was delivered by CPMT representatives Dr William Chen, Prof Klaus-Jürgen Wolter and Dr Ricky Lee during the luncheon talk on 8th December 2005.

Four professional short courses were also organized in conjunction with the conference, namely (1) Wirebonding in Microelectronics with Emphasis on Cu Low K, (2) Lead Free Solder Materials and Reliability Performance, (3) Drop Impact Modeling and Testing for Handheld Electronic Products at Board and System Levels, and (4) Wafer Level Packaging. A total of 87 delegates participated in the short courses on 7 December 2005. This is by far the best turn-out for any EPTC-organized short courses.

The chapter has also planned the 13th International Symposium on the Physical and Failure Analysis of Integrated Circuits (IPFA 2006), to be held on 3 to 7 July 2006 at the Meritus Mandarin Hotel at Singapore.

Join us at the 8th EPTC, 6-8 December, 2006, at the Pan Pacific Hotel, Singapore. See the Call for Papers [later in this Newsletter](#).



Members of IAB and IEEE CPMT at EPTC 2005

From left to right : Dr Mahadevan, Dr William Chen, Prof Andrew Tay, Swee Yong Khim, Dr C.P. Wong, Rolf Aschenbrenner, Dr Ricky Lee and Dr Lim Thiam Beng



Dr. Ong and some of the Executive members of Chapter and IPFA at the farewell function.

India Council Chapter:

India council chapter executive committee has been reorganized in December 2005. Prof. M. M. Shah has taken over as chairman for the chapter and Dr. P. B. Parikh has agreed to extend services as secretary/Treasurer for the chapter.